

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **07-321188**

(43)Date of publication of application : **08.12.1995**

(51)Int.Cl. **H01L 21/68**

B23Q 3/15

H01L 21/027

(21)Application number : **07-032015** (71)Applicant : **INTERNATL BUSINESS
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(30)Priority

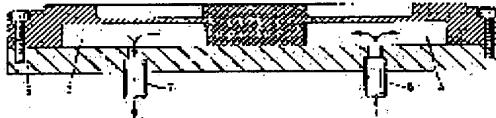
Priority number : **94 241527** Priority date : **12.05.1994** Priority country : **US**

**(54) APPARATUS FOR COATING SURFACE OF ELECTROSTATIC CHUCK
WITH LAYER OF DIELECTRIC SUBSTANCE**

(57)Abstract:

PURPOSE: To provide an electrostatic wafer chuck which is strictly controlled exerting a preliminarily set attraction force when a voltage is applied, by circulating a coolant through a recessed part at a rear face of the chuck during an anodic oxidation process.

CONSTITUTION: A closed back plate is replaceable with a back plate 5 which has an opening to allow a fluid coolant to enter from an injection opening 6 and come out of a discharge opening through an enclosed recessed part 3. A chuck is kept at a uniform temperature in its entirety during an anodic oxidation process, so that a uniform plating (anodic oxidation) thickness is ensured all over a surface of the chuck. Accordingly, an electrostatic attraction force acting between a wafer and the chuck can be controlled in size better.



LEGAL STATUS

[Date of request for examination] 15.04.1997

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 2878144

[Date of registration] 22.01.1999

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]